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# Thyristor Modules

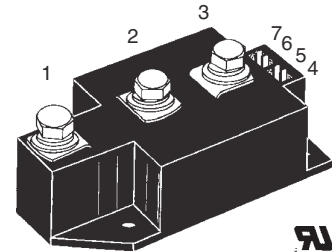
## Thyristor/Diode Modules

$$I_{TRMS} = 2 \times 450 \text{ A}$$

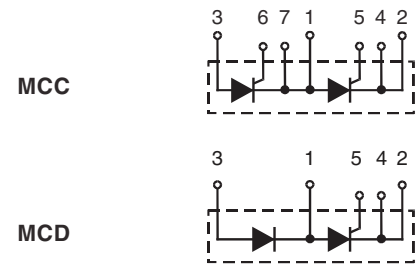
$$I_{TAVM} = 2 \times 287 \text{ A}$$

$$V_{RRM} = 800-1800 \text{ V}$$

$V_{RSM}$ $V_{DSM}$ V	$V_{RRM}$ $V_{DRM}$ V	Type	Version 1	Version 1
900	800	MCC 250-08io1	MCC 250-08io1	MCD 250-08io1
1300	1200	MCC 250-12io1	MCC 250-12io1	MCD 250-12io1
1500	1400	MCC 250-14io1	MCC 250-14io1	MCD 250-14io1
1700	1600	MCC 250-16io1	MCC 250-16io1	MCD 250-16io1
1900	1800	MCC 250-18io1	MCC 250-18io1	MCD 250-18io1



Symbol	Conditions	Maximum Ratings	
$I_{TRMS}, I_{FRMS}$ $I_{TAVM}, I_{FAVM}$	$T_{VJ} = T_{VJM}$ $T_C = 85^\circ\text{C}; 180^\circ \text{ sine}$	450	A
$I_{TSM}, I_{FSM}$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0$	$t = 10 \text{ ms (50 Hz), sine}$ $t = 8.3 \text{ ms (60 Hz), sine}$	9000 9600 A A
$\int i^2 dt$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0$	$t = 10 \text{ ms (50 Hz), sine}$	405 000 $\text{A}^2\text{s}$
		$t = 8.3 \text{ ms (60 Hz), sine}$	380 000 $\text{A}^2\text{s}$
$(di/dt)_{cr}$	$T_{VJ} = T_{VJM};$ $f = 50 \text{ Hz}; t_p = 200 \mu\text{s}$ $V_D = 2/3 V_{DRM}$	repetitive, $I_T = 860 \text{ A}$	100 $\text{A}/\mu\text{s}$
		$I_G = 1 \text{ A};$ $di_G/dt = 1 \text{ A}/\mu\text{s}$	non repetitive, $I_T = 290 \text{ A}$
$(dv/dt)_{cr}$	$T_{VJ} = T_{VJM};$ $R_{GK} = \infty; \text{ method 1 (linear voltage rise)}$	$V_{DR} = 2/3 V_{DRM}$	1000 $\text{V}/\mu\text{s}$
$P_{GM}$	$T_{VJ} = T_{VJM};$ $I_T = I_{TAVM};$	$t_p = 30 \mu\text{s}$ $t_p = 500 \mu\text{s}$	120 W 60 W
$P_{GAV}$			20 W
$V_{RGM}$			10 V
$T_{VJ}$			-40...+140 $^\circ\text{C}$
$T_{VJM}$			140 $^\circ\text{C}$
$T_{stg}$			-40...+125 $^\circ\text{C}$
$V_{ISOL}$	50/60 Hz, RMS; $I_{ISOL} \leq 1 \text{ mA};$	$t = 1 \text{ min}$	3000 V~
		$t = 1 \text{ s}$	3600 V~
$M_d$	Mounting torque (M5)		2.5-5/22-44 $\text{Nm}/\text{lb.in.}$
	Terminal connection torque (M8)		12-15/106-132 $\text{Nm}/\text{lb.in.}$
<b>Weight</b>	Typical including screws		320 g



### Features

- International standard package
- Direct copper bonded  $\text{Al}_2\text{O}_3$ -ceramic base plate
- Planar passivated chips
- Isolation voltage 3600 V~
- UL registered, E 72873
- Keyed gate/cathode twin pins

### Applications

- Motor control
- Power converter
- Heat and temperature control for industrial furnaces and chemical processes
- Lighting control
- Contactless switches

### Advantages

- Space and weight savings
- Simple mounting
- Improved temperature and power cycling
- Reduced protection circuits

Data according to IEC 60747 and refer to a single thyristor/diode unless otherwise stated. IXYS reserves the right to change limits, test conditions and dimensions



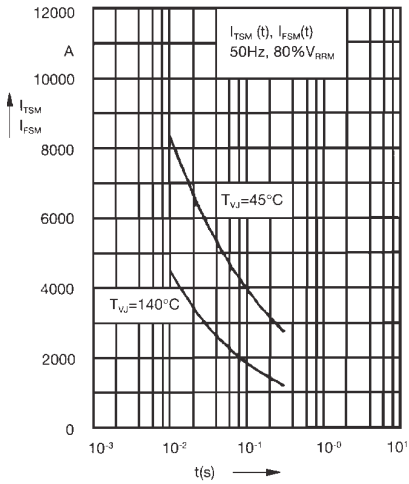


Fig. 3 Surge overload current  
 $I_{TSM}, I_{FSM}$ : Crest value,  $t$ : duration

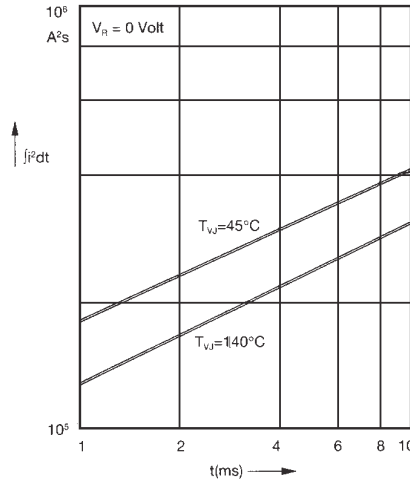


Fig. 4  $\int j^2 dt$  versus time (1-10 ms)

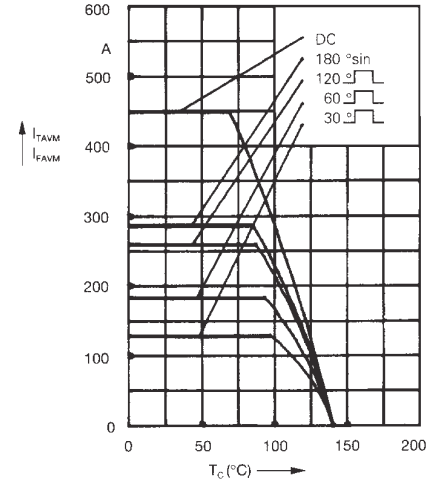


Fig. 4a Maximum forward current at case temperature

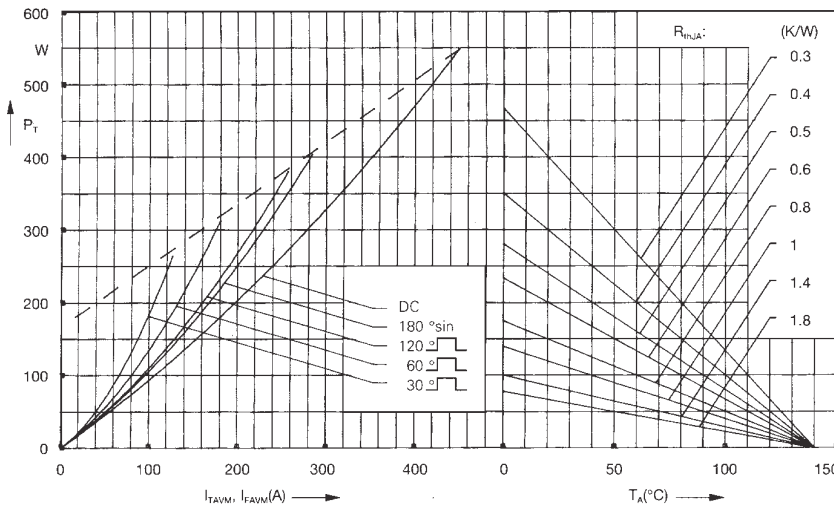


Fig. 5 Power dissipation versus on-state current and ambient temperature (per thyristor or diode)

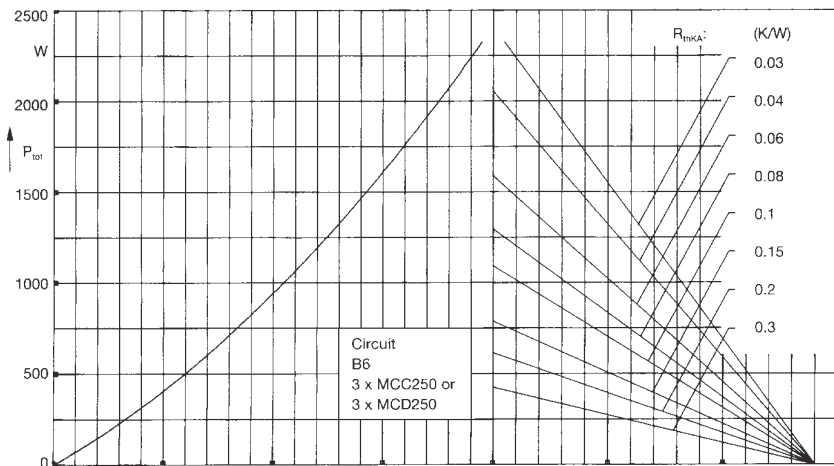


Fig. 6 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

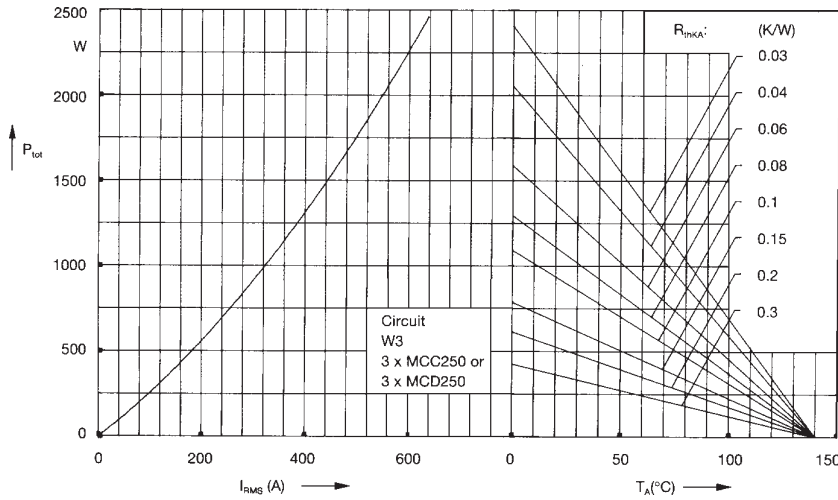


Fig. 7 Three phase AC-controller:  
Power dissipation versus RMS  
output current and ambient  
temperature

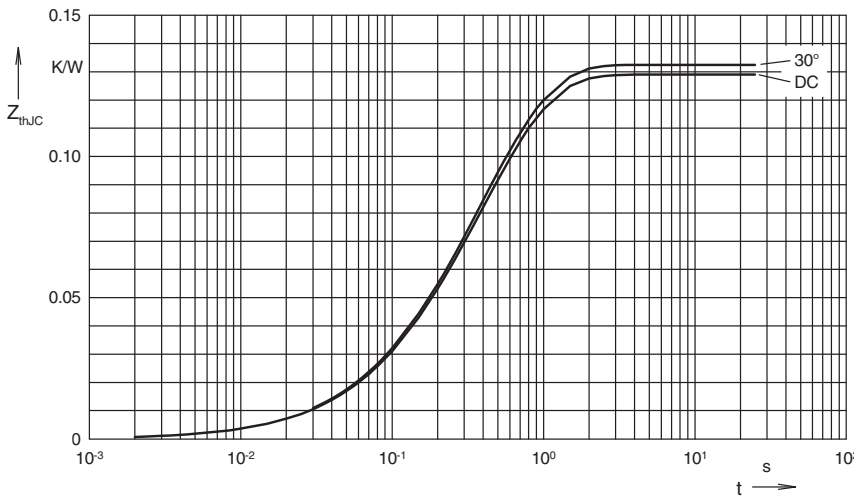


Fig. 8 Transient thermal impedance  
junction to case (per thyristor or  
diode)

$R_{thJC}$  for various conduction angles  $d$ :

$d$	$R_{thJC}$ (K/W)
DC	0.129
180°C	0.131
120°C	0.131
60°C	0.132
30°C	0.132

Constants for  $Z_{thJC}$  calculation:

$i$	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.0035	0.099
2	0.0165	0.168
3	0.1091	0.456

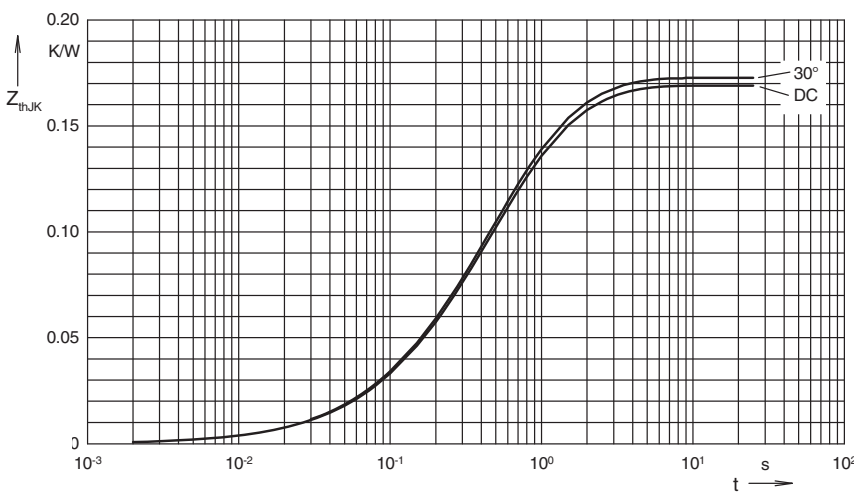


Fig. 9 Transient thermal impedance  
junction to heatsink (per thyristor or  
diode)

$R_{thJK}$  for various conduction angles  $d$ :

$d$	$R_{thJK}$ (K/W)
DC	0.169
180°C	0.171
120°C	0.172
60°C	0.172
30°C	0.173

Constants for  $Z_{thJK}$  calculation:

$i$	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.0033	0.099
2	0.0159	0.168
3	0.1053	0.456
4	0.04	1.36